

## Packaging for Automotive Electronics – Challenges and Trends



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### Abstract :

Since years automotive ICs were using standard packages, which had been developed earlier for consumer products. The main challenge was to achieve the robustness needed in automotive environment. Since miniaturization became a driving factor for automotive products too, specific packaging solutions are required. On this path the need for superior reliability asks for re-thinking the classical approach of putting a die just into some housing. Designing the whole system from die through package to PCB, taking into account the individual interaction is key. The presentation will give insight into this approach for recent development projects at Infineon Technologies.

### Speaker's Biography :

Jens Oetjen holds a Master in Electrical Engineering, from the Technical University of Braunschweig, Germany and PhD, Technical University of Braunschweig, Germany. He joined Siemens Semiconductor division, Munich which was later known as Infineon Technologies (year 2000). He started as a Product development engineer for discrete IGBT and MOSFET products and went on to lead a test engineering group for the discrete IGBT and MOSFET products.

He held the role of overall project manager for the lead-free conversion project in Infineon's Automotive Division and then was the platform project manager for packaging development projects in the Automotive Division. He is currently the Head of "Package Technology Concepts", Automotive Division for Infineon Technologies in Munich, Germany.